

Electrical Performance

Parameter		Min.	Typ.	Max.	Units	Notes
Output Frequency		1		166	MHz	As specified
Supply Voltage		+2.25	+2.50	+2.75	V	
Supply Current, Output Enabled				15	mA	1 to 32 MHz
				25		32 to 50 MHz
				35		50 to 166 MHz
Supply Current, Standby Mode				10	μA	Output Hi-Z
Frequency Stability				±20 to ±50	ppm	See Note 1 below
Operating Temperature Range		-20		+70	°C	Commercial (standard)
		-40		+85		Industrial (standard)
Output Logic 0, V _{OL}				10% V _{DD}	V	
Output Logic 1, V _{OH}		90% V _{DD}			V	
Output Load				15	pF	
Duty Cycle		45		55	%	Measured 50% V _{DD}
Rise and Fall Time	up to 32 MHz			7	ns	Measured 20/80% of waveform
	32 to 70 MHz			5		
	70 to 166 MHz			3		
Jitter, Phase	1 to 166 MHz			1	ps RMS (1-σ)	10kHz to 20 MHz frequency band
Jitter, Accumulated	up to 80 MHz			5	ps RMS (1-σ)	20,000 adjacent periods
	80 to 166 MHz			3		
Jitter, Total	up to 80 MHz			50	ps pk-pk	100,000 random periods
	80 to 166 MHz			30		

Notes:

- Stability includes all combinations of operating temperature, load changes, rated input (supply) voltage changes, initial calibration tolerance (25°C), aging (1 year at 25°C average effective ambient temperature), shock and vibration.
- For specifications other than those listed, please contact sales.

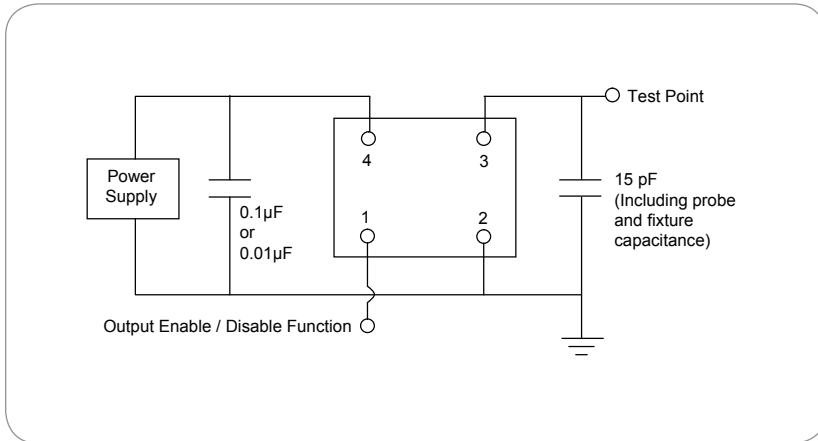
Output Enable / Disable Function

Parameter	Min.	Typ.	Max.	Units	Notes
Input Voltage (pin 1), Output Enable	0.7 V _{DD}			V	or open
Input Voltage (pin 1), Output Disable (low power standby)			0.3 V _{DD}	V	Output is Hi-Z
Internal Pullup Resistance	50			kΩ	
Output Disable Delay			100	ns	
Output Enable Delay			10	ms	

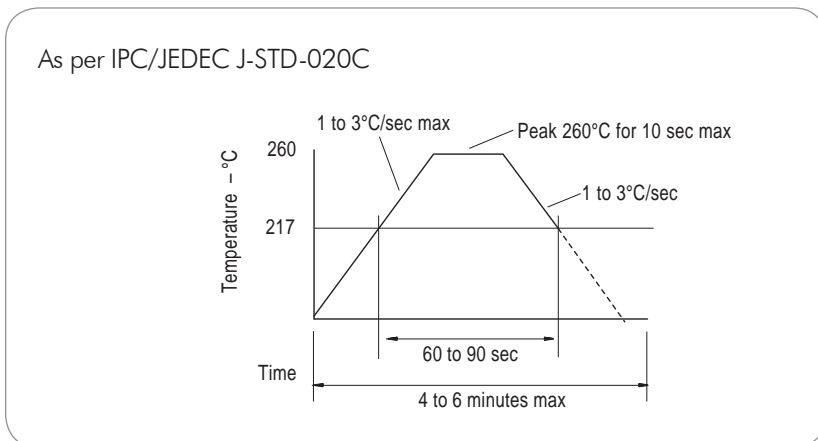
Absolute Maximum Ratings

Parameter	Min.	Typ.	Max.	Units	Notes
Storage Temperature	-55		+125	°C	

Test Circuit



Reflow Soldering Profile



Reliability Test Ratings

This product is rated to meet the following test conditions:

Type	Parameter	Test Condition
Mechanical	Shock	MIL-STD-883, Method 2002, Condition B
Mechanical	Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Mechanical	Terminal strength	MIL-STD-883, Method 2004, Condition D
Mechanical	Gross leak	MIL-STD-883, Method 1014, Condition C
Mechanical	Fine leak	MIL-STD-883, Method 1014, Condition A2 ($R_1 = 2 \times 10^{-8}$ atm cc/s)
Mechanical	Solvent resistance	MIL-STD-202, Method 215
Environmental	Thermal shock	MIL-STD-883, Method 1011, Condition A
Environmental	Moisture resistance	MIL-STD-883, Method 1004
Environmental	Vibration	MIL-STD-883, Method 2007, Condition A
Environmental	Resistance to soldering heat	J-STD-020C Table 5-2 Pb-free devices (2 cycles max)